

## HX426C16FB3K4/16

16GB (4GB 512M x 64-Bit x 4 pcs.)

DDR4-2666 CL16 288-Pin DIMM Kit



## SPECIFICATIONS

CL(IDD)	16 cycles
Row Cycle Time (tRCmin)	45.75ns(min.)
Refresh to Active/Refresh Command Time (tRFCmin)	260ns(min.)
Row Active Time (tRASmin)	29.25ns(min.)
UL Rating	94 V - 0
Operating Temperature	0° C to +85° C
Storage Temperature	-55° C to +100° C

## DESCRIPTION

HyperX HX426C16FB3K4/16 is a kit of four 512M x 64-bit (4GB) DDR4-2666 CL16 SDRAM (Synchronous DRAM) 1Rx8, memory module, based on eight 512M x 8-bit FBGA components per module. Each module kit supports Intel® Extreme Memory Profiles (Intel® XMP) 2.0. Total kit capacity is 16GB. Each module has been tested to run at DDR4-2666 at a low latency timing of 16-18-18 at 1.2V. Additional timing parameters are shown in the Plug-N-Play (PnP) Timing Parameters section below. The JEDEC standard electrical and mechanical specifications are as follows:

**Note:** The PnP feature offers a range of speed and timing options to support the widest variety of processors and chipsets. Your maximum speed will be determined by your BIOS.

## FEATURES

- Power Supply: VDD = 1.2V Typical
- VDDQ = 1.2V Typical
- VPP = 2.5V Typical
- VDDSPD = 2.2V to 3.6V
- On-Die termination (ODT)
- 16 internal banks; 4 groups of 4 banks each
- Bi-Directional Differential Data Strobe
- 8 bit pre-fetch
- Burst Length (BL) switch on-the-fly BL8 or BC4(Burst Chop)
- Height 1.3425" (34.1mm), w/heatsink

## FACTORY TIMING PARAMETERS

- Default (Plug N Play): DDR4-2666 CL16-18-18 @1.2V
- XMP Profile #1: DDR4-2666 CL16-18-18 @1.2V

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